All Programmable 7 Series Product Selection Guide







Spartan-7 FPGAs

I/O Optimization at the Lowest Cost and Highest Performance-per-Watt (1.0V, 0.95V)

	Part Number	XC7S6	XC7S15	XC7S25	XC7S50	XC7S75	XC7S100
	Logic Cells	6,000	12,800	23,360	52,160	76,800	102,400
Logic Resources	Slices	938	2,000	3,650	8,150	12,000	16,000
	CLB Flip-Flops	7,500	16,000	29,200	65,200	96,000	128,000
	Max. Distributed RAM (Kb)	70	150	313	600	832	1,100
Memory Resources	Block RAM/FIFO w/ ECC (36 Kb each)	5	10	45	75	90	120
	Total Block RAM (Kb)	180	360	1,620	2,700	3,240	4,320
Clock Resources	Clock Mgmt Tiles (1 MMCM + 1 PLL)	2	2	3	5	8	8
./0.0	Max. Single-Ended I/O Pins	100	100	150	250	400	400
I/O Resources	Max. Differential I/O Pairs	48	48	72	120	192	192
	DSP Slices	10	20	80	120	140	160
Embedded Hard IP Resources	Analog Mixed Signal (AMS) / XADC	0	0	1	1	1	1
	Configuration AES / HMAC Blocks	0	0	1	1	1	1
	Commercial Temp (C)	-1,-2	-1,-2	-1,-2	-1,-2	-1,-2	-1,-2
Speed Grades	Industrial Temp (I)	-1,-2,-1L	-1,-2,-1L	-1,-2,-1L	-1,-2,-1L	-1,-2,-1L	-1,-2,-1L
	Expanded Temp (Q)	-1	-1	-1	-1	-1	-1

	Body Area	Ball Pitch													
Package ⁽¹⁾	(mm)	(mm)		Available User I/O: 3.3V SelectIO™ HR I/O											
CPGA196	8x8	0.5	100	100											
CSGA225	13x13	0.8	100	100	150										
CSGA324	15x15	0.8			150	210									
FTGB196	15x15	1.0	100	100	100	100									
FGGA484	23x23	1.0				250	338	338							
FGGA676	27x27	1.0					400	400							

Notes

^{1.} Packages with the same last letter and number sequence, e.g., A484, are footprint compatible with all other Spartan-7 devices with the same sequence. The footprint compatible devices within this family are outlined.

Artix-7 FPGAs

Transceiver Optimization at the Lowest Cost and Highest DSP Bandwidth (1.0V, 0.95V, 0.9V)

		Pai	rt Number	XC7A12T	XC7A15T	XC7A25T	XC7A35T	XC7A50T	XC7A75T	XC7A100T	XC7A200T
	Logic Cells		12,800	16,640	23,360	33,280	52,160	75,520	101,440	215,360	
Logic Resources			Slices	2,000	2,600	3,650	5,200	8,150	11,800	15,850	33,650
Nesources	CLB Flip-Flops			16,000	20,800	29,200	41,600	65,200	94,400	126,800	269,200
	Maximum Distributed RAM (Kb)			171	200	313	400	600	892	1,188	2,888
Memory Resources	Block RAM/FIF	O w/ ECC (30	6 Kb each)	20	25	45	50	75	105	135	365
Nesources		Total Block	RAM (Kb)	720	900	1,620	1,800	2,700	3,780	4,860	13,140
Clock Resources	CI	MTs (1 MMC	M + 1 PLL)	3	5	3	5	5	6	6	10
I/O Resources	Maxi	mum Single-	Ended I/O	150	250	150	250	250	300	300	500
i/O Resources	Maximui	m Differentia	al I/O Pairs	72	120	72	120	120	144	144	240
			DSP Slices	40	45	80	90	120	180	240	740
		PCle® Gen2 ⁽¹⁾			1	1	1	1	1	1	1
Embedded Hard IP	Analog Mixed Signal (AMS) / XADC			1	1	1	1	1	1	1	1
Resources	Configuration AES / HMAC Blocks			1	1	1	1	1	1	1	1
	GTP Transceivers (6.6 Gb/s Max Rate) ⁽²⁾			2	4	4	4	4	8	8	16
	Commercial Temp (C)			-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2
Speed Grades		Extended Temp (E)			-2L, -3						
		Industria	al Temp (I)	-1, -2, -1L							
	Package ^{(3), (4)}	Dimensions (mm)	Ball Pitch (mm)			eivers)					
	CPG236	10 x 10	0.5		106 (2)		106 (2)	106 (2)			
	CPG238	10 x 10	0.5	112 (2)		112 (2)					
	CSG324	15 x 15	0.8		210 (0)		210 (0)	210 (0)	210 (0)	210 (0)	
	CSG325	15 x 15	0.8	150 (2)	150 (4)	150 (4)	150 (4)	150 (4)			
	FTG256	17 x 17	1.0		170 (0)		170 (0)	170 (0)	170 (0)	170 (0)	
	SBG484	SBG484 19 x 19 0.8									285 (4)
Footprint	FGG484 ⁽⁵⁾	23 x 23	1.0		250 (4)		250 (4)	250 (4)	285 (4)	285 (4)	
Compatible	FBG484 ⁽⁵⁾	23 x 23	1.0								285 (4)
Footprint	FGG676 ⁽⁶⁾	27 x 27	1.0						300 (8)	300 (8)	
Compatible	FBG676 ⁽⁶⁾	27 x 27	1.0								400 (8)
	FFG1156	35 x 35	1.0								500 (16)

1. Supports PCI Express Base 2.1 specification at Gen1 and Gen2 data rates.

- 2. Represents the maximum number of transceivers available. Note that the majority of devices are available without transceivers. See the Package section of this table for details.
- 3. Leaded package option available for all packages. See DS180, 7 Series FPGAs Overview for package details.
- 4. Device migration is available within the Artix-7 family for like packages but is not supported between other 7 series families.
- 5. Devices in FGG484 and FBG484 are footprint compatible.
- 6. Devices in FGG676 and FBG676 are footprint compatible.



Kintex-7 FPGAs

Optimized for Best Price-Performance (1.0V, 0.95V, 0.9V)

			Part Number	XC7K70T	XC7K160T	XC7K325T	XC7K355T	XC7K410T	XC7K420T	XC7K480T
	EasyPath™	Cost Reducti	on Solutions ⁽¹⁾	_	_	XCE7K325T	XCE7K355T	XCE7K410T	XCE7K420T	XCE7K480T
			Slices	10,250	25,350	50,950	55,650	63,550	65,150	74,650
Logic Resources			Logic Cells	65,600	162,240	326,080	356,160	406,720	416,960	477,760
			CLB Flip-Flops	82,000	202,800	407,600	445,200	508,400	521,200	597,200
	Max	ıimum Distribu	uted RAM (Kb)	838	2,188	4,000	5,088	5,663	5,938	6,788
Memory Resources	Block RAI	M/FIFO w/ EC	C (36 Kb each)	135	325	445	715	795	835	955
		Total B	lock RAM (Kb)	4,860	11,700	16,020	25,740	28,620	30,060	34,380
Clock Resources		CMTs (1 M	IMCM + 1 PLL)	6	8	10	6	10	8	8
I/O Resources	Maximum Single-Ended I/O			300	400	500	300	500	400	400
i/O Resources	Maximum Differential I/O Pairs			144	192	240	144	240	192	192
	DSP48 Slices			240	600	840	1,440	1,540	1,680	1,920
	PCIe® Gen2 ⁽²⁾			1	1	1	1	1	1	1
Integrated IP Resources	Analog Mixed Signal (AMS) / XADC			1	1	1	1	1	1	1
	Configuration AES / HMAC Blocks			1	1	1	1	1	1	1
	GTX Transceivers (12.5 Gb/s		b/s Max Rate)	8	8	16	24	16	32	32
	Commercial Temp (C)			-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2
Speed Grades	Extended Temp (E)			-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3
		Indu	strial Temp (I)	-1, -2	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L	-1, -2, -2L
_	Package ⁽³⁾	Dimensions (mm)	Ball Pitch (mm)	Available User I/O: 3.3V HR I/O, 1.8V HP I/Os (GTX)						
	FBG484 ⁽⁴⁾	23 x 23	1.0	185, 100 (4)	185, 100 (4)					
Footprint	FBG676 ⁽⁴⁾	27 x 27	1.0	200, 100 (8)	250, 150 (8)	250, 150 (8)		250, 150 (8)		
Compatible	FFG676	27 x 27	1.0		250, 150 (8)	250, 150 (8)		250, 150 (8)		
Footprint	FBG900 ⁽⁴⁾	31 x 31	1.0			350, 150 (16)		350, 150 (16)		
Compatible	FFG900	31 x 31	1.0			350, 150 (16)		350, 150 (16)		
	FFG901	31 x 31	1.0				300, 0 (24)		380, 0 (28)	380, 0 (28)

Notes:

FFG1156

1. EasyPath™ solutions provide a fast and conversion-free path for cost reduction.

1.0

- 2. Hard block supports PCI Express Base 2.1 specification at Gen1 and Gen2 data rates. Gen3 supported with soft IP.
- 3. See <u>DS180</u>, 7 Series FPGAs Overview, for package details.

35 x 35

4. GTX transceivers in FB packages support the following maximum data rates: 10.3Gb/s in FBG484; 6.6Gb/s in FBG676 and FBG900. See <u>DS182</u>, Kintex-7 FPGAs Data Sheet: DC and AC Switching Characteristics, for details,



400, 0 (32)

400, 0 (32)

Virtex-7 FPGAs

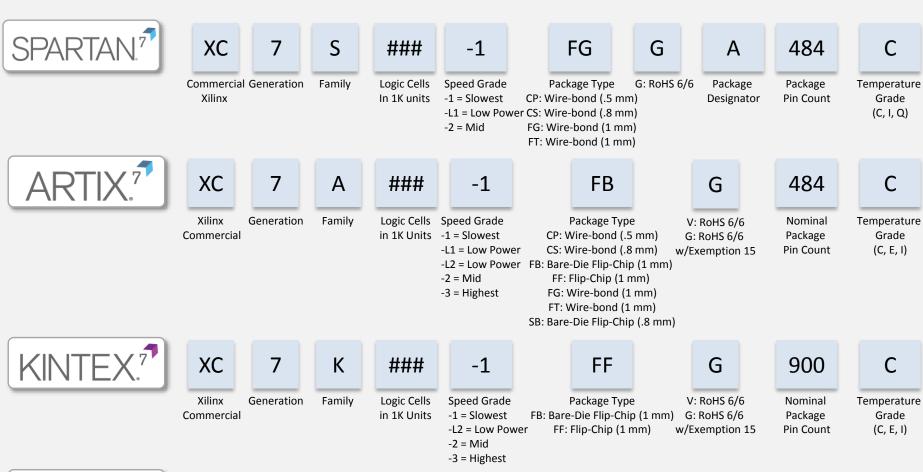
	Optimized for Highest System Performance and Capacity (1.0V)													
			Part Number	XC7V585T	XC7V2000T	XC7VX330T	XC7VX415T	XC7VX485T	XC7VX550T	XC7VX690T	XC7VX980T	XC7VX1140T	YC7\/H580T	XC7VH870T
	FasyPath™	Cost Reductio		XCE7V585T	—				XCE7VX550T		XCE7VX980T	- AC7 VX11401	—	—
	Lusyi utii	COSt Neddello	Slices	91,050	305,400	51,000	64,400	75,900	86,600	108,300	153,000	178,000	90,700	136,900
Logic			Logic Cells	582,720	1,954,560	326,400	412,160	485,760	554,240	693,120	979,200	1,139,200	580,480	876,160
Resources		(CLB Flip-Flops	728,400	2,443,200	408,000	515,200	607,200	692,800	866,400	1,224,000	1,424,000	725,600	1,095,200
	May	imum Distribu		6,938	21,550	4,388	6,525	8,175	8,725	10,888	13,838	17,700	8,850	13,275
Memory		M/FIFO w/ ECC	٠,	795	1,292	750	880	1,030	1,180	1,470	1,500	1,880	940	1,410
Resources	Diock 10 ti	•	ock RAM (Kb)	28,620	46,512	27,000	31,680	37,080	42,480	52,920	54,000	67,680	33,840	50,760
Clocking			MCM + 1 PLL)	18	24	14	12	14	20	20	18	24	12	18
1/0		Maximum Sing		850	1,200	700	600	700	600	1,000	900	1,100	600	300
Resources		kimum Differer		408	576	336	288	336	288	480	432	528	288	144
			DSP Slices	1,260	2,160	1,120	2,160	2,800	2,880	3,600	3,600	3,360	1,680	2,520
			PCIe® Gen2 ⁽²⁾	3	4	_	_	4	_	_	_	_	_	_
			PCIe Gen3	_	_	2	2	_	2	3	3	4	2	3
Integrated IP	Analog	Mixed Signal ((AMS) / XADC	1	1	1	1	1	1	1	1	1	1	1
Resources	Config	guration AES /	HMAC Blocks	1	1	1	1	1	1	1	1	1	1	1
		vers (12.5 Gb/s		36	36	_	_	56	_	_	_	_	_	_
		vers (13.1 Gb/s		_	_	28	48	_	80	80	72	96	48	72
	GTZ Transcei	vers (28.05 Gb	o/s Max Rate)	_	_	_	_	_	_	_	_	_	8	16
C I		Commer	cial Temp (C)	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2
Speed		Extende	ed Temp (E) ⁽⁵⁾	-2L, -3	-2L, -2G	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L, -3	-2L	-2L, -2G	-2L, -2G	-2L, -2G
Grades		Indus	strial Temp (I)	-1, -2	-1	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1	-1	_	_
·	Package ⁽⁶⁾	Dimensions	Ball Pitch			Assailah	la Haar I/O. 2	3V HR I/O, 1.8\	/ LID L/Os /CTV	CTU\			1.8V HP I/O	VCTU CT7\
_		(mm)	(mm)			Availab	ile User 1/U. 5.	3V HK 1/U, 1.6	V HP 1/OS (G1X	, отп)			1.60 HP 1/0	(GIH, GIZ)
	FFG1157 ⁽⁷⁾	35 x 35	1.0	0, 600 (20, 0)		0, 600 (0, 20)	0, 600 (0, 20)	0, 600 (20, 0)		0, 600 (0, 20)				
Footprint	FFG1761 ⁽⁷⁾	42.5 x 42.5	1.0	100, 750 (36, 0)		50, 650 (0, 28)		0, 700 (28, 0)		0, 850 (0, 36)				
Compatible	FHG1761	45 x 45	1.0		0, 850 (36, 0)									
	FLG1925	45 x 45	1.0		0, 1200 (16, 0)									
	FFG1158 ⁽⁷⁾	35 x 35	1.0				0, 350 (0, 48)	0, 350 (48, 0)	0, 350 (0, 48)					
Footprint	FFG1926	45 x 45	1.0							0, 720 (0, 64)	0, 720 (0, 64)			
Compatible	FLG1926	45 x 45	1.0									0, 720 (0, 64)		
	FFG1927 ⁽⁷⁾	45 x 45	1.0				0, 600 (0, 48)	0, 600 (56, 0)	0, 600 (0, 80)	0, 600 (0, 80)				
Footprint	FFG1928	45 x 45	1.0								0, 480 (0, 72)	0. 100 (0. 65)		
Compatible	FLG1928	45 x 45	1.0					0. 700 (04.0)		0. 1000 (0. 5.1)	0.000 (0.51)	0, 480 (0, 96)		
Footprint	FFG1930	45 x 45	1.0					0, 700 (24, 0)		0, 1000 (0, 24)		0.4400 (0.04)		
Compatible	FLG1930	45 x 45	1.0									0, 1100 (0, 24)	400 (24 6)	
	FLG1155	35 x 35	1.0										400 (24, 8)	
	FLG1931	45 x 45	1.0										600 (48, 8)	200 (72, 16)
_	FLG1932	45 x 45	1.0											300 (72, 16)

Notes:

- 1. EasyPath™ solutions provide a fast and conversion-free path for cost reduction.
- 2. Hard block supports PCI Express Base 2.1 specification at Gen1 and Gen2 data rates. Gen3 supported with soft IP.
- 3. 12.5 Gb/s support in "-3E", "-2GE" speed/temperature grade; 10.3125 Gb/s support in "2C", "-2LE", and "-2I" speed grade.
- 4. 13.1 Gb/s support in "-3E". "-2GE" speed grade; 11.3 Gb/s support in "2C", "-2LE" and "-2I" speed/temperature grades.
- -2G only applies to Stacked Silicon Interconnect devices and supports 12.5G GTX, 13.1G GTH, 28.05G GTZ with -2 fabric.
- de. 6. Leaded package options ("FFxxxx",""FLxxxx",""FHxxxx") available for all packages. "HCxxxx" is not offered in a leaded option.
 - 7. See DS180, 7 Series FPGAs Overview for package details.



Device Ordering Information





XC

Xilinx

Commercial

Generation

Family

###

in 1K Units

Logic Cells

-1 Speed Grade

-1 = Slowest

-3 = Highest

-L2 = Low Power

-2 = Mid

FF Package Type

FL: Flip-Chip (1 mm)

FF: Flip-Chip (1 mm) FH: Flip-Chip (1 mm)

V: RoHS 6/6 G: RoHS 6/6 w/Exemption 15

G

1156 Nominal

Package

Pin Count

Temperature Grade (C, E, I)

C

Notes:

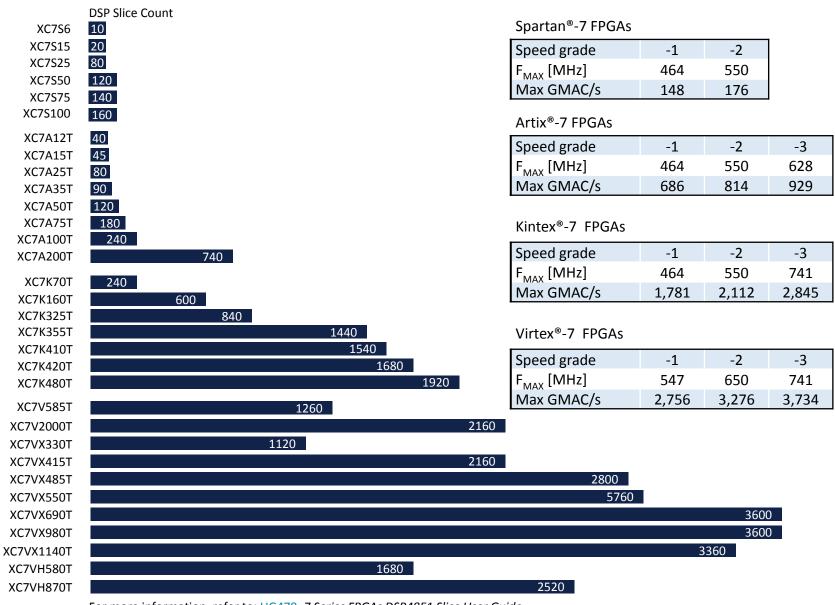
-L1 is the ordering code for the lower power, -1L speed grade.

-L2 is the ordering code for the lower power, -2L speed grade.

C = Commercial (Tj = 0° C to +85°C) E = Extended (Tj = 0° C to +100°C) I = Industrial (Tj = -40° C to +100°C)

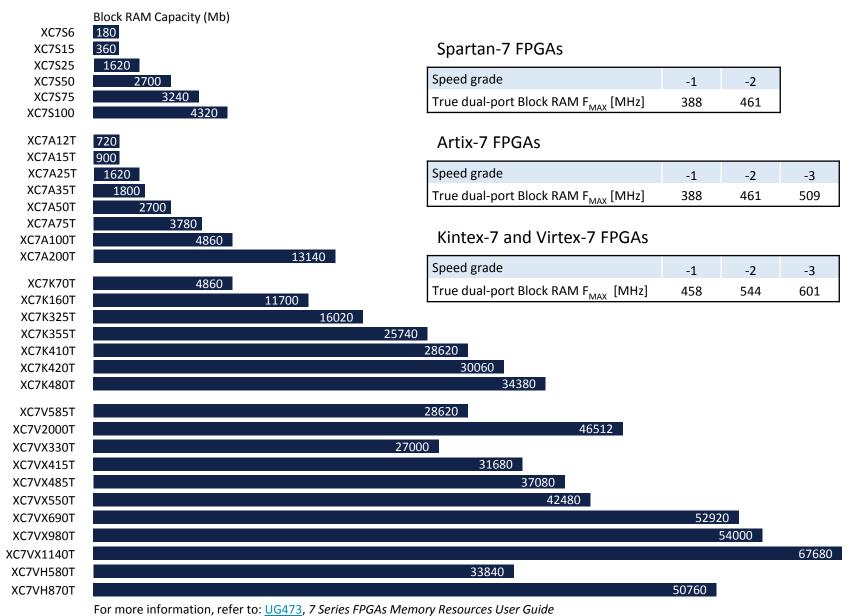
HC: Ceramic Flip-Chip (1 mm) Q = Expanded (Tj = -40°C to +125°C)

Digital Signal Processing Metrics



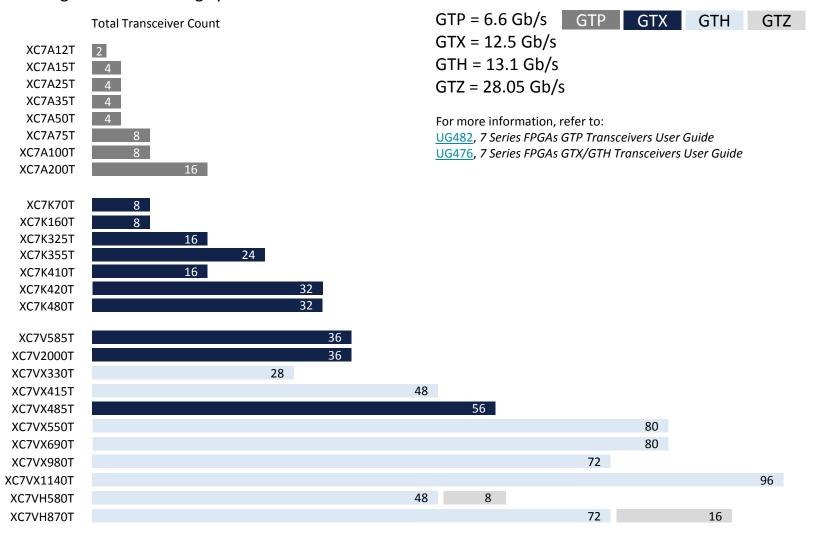
For more information, refer to: <u>UG479</u>, 7 Series FPGAs DSP48E1 Slice User Guide
Important: Verify all data in this document with the device data sheets found at www.xilinx.com

Block RAM Metrics



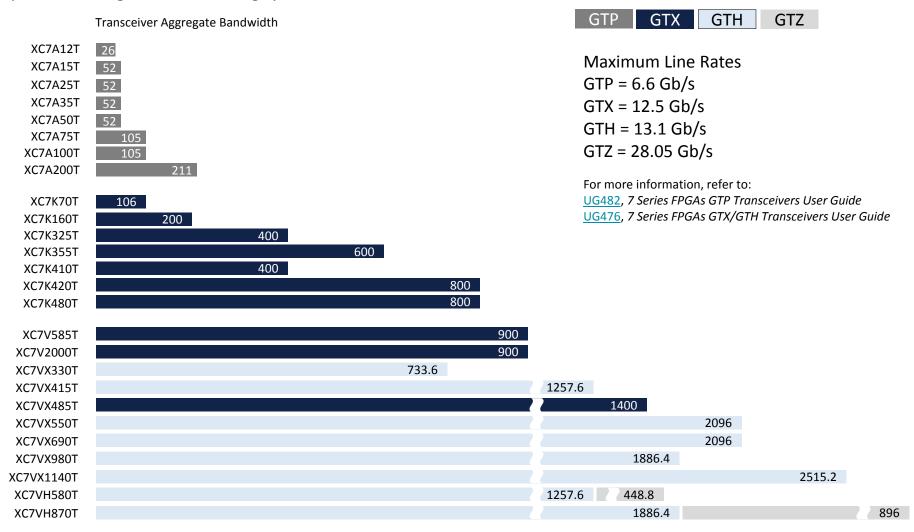
High-Speed Serial Transceivers

7 series devices provide a broad portfolio of transceivers for applications ranging from low-cost consumer products to high-end networking systems.

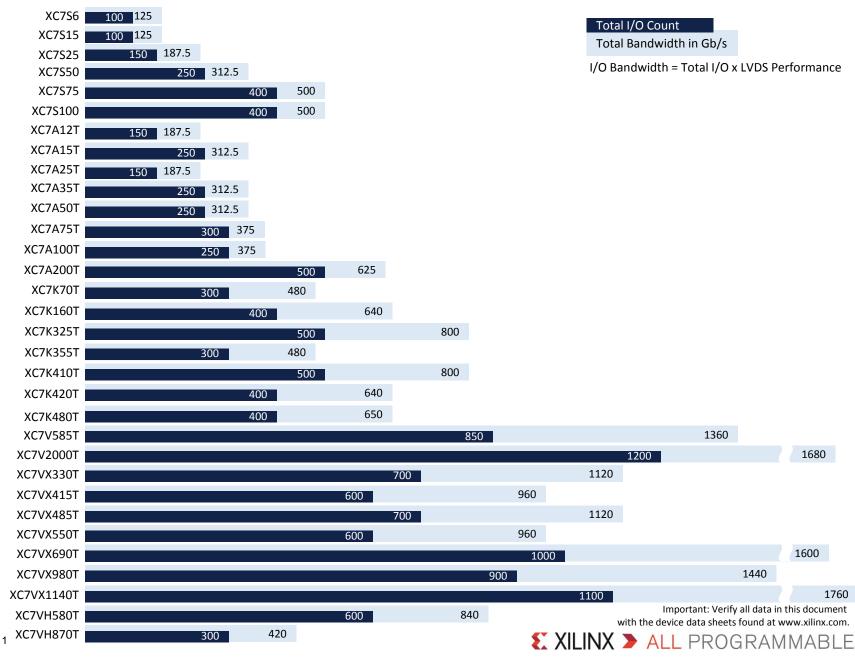


Transceiver Aggregate Bandwidth

7 series devices provide a broad portfolio of transceivers for applications ranging from low-cost consumer products to high-end networking systems.



I/O Count and Bandwidth



References

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DS180, 7 Series FPGAs Overview
DS181, Artix-7 FPGAs Data Sheet: DC and AC Switching Characteristics
DS182, Kintex-7 FPGAs Data Sheet: DC and AC Switching Characteristics
DS183, Virtex-7 T and XT FPGAs Data Sheet: DC and AC Switching Characteristics
UG470, 7 Series FPGAs Configuration User Guide
UG471, 7 Series FPGAs SelectIO Resources User Guide
UG472, 7 Series FPGAs Clocking Resources User Guide
UG473, 7 Series FPGAs Memory Resources User Guide
UG474, 7 Series FPGAs Configurable Logic Block User Guide
UG475, 7 Series FPGAs Packaging and Pinout User Guide
UG476, 7 Series FPGAs GTX/GTH Transceivers User Guide
UG479, 7 Series FPGAs DSP48E1 Slice User Guide
UG480, 7 Series FPGAs and Zyng-7000 All Programmable SoC XADC Dual 12-Bit 1 MSPS ADC User Guide
UG482, 7 Series FPGAs GTP Transceivers User Guide
UG483, 7 Series FPGAs PCB Design Guide
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XMP101 (v1.7)

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